

LAMINATE, METHOD FOR MANUFACTURING LAMINATE, HOLLOW STRUCTURE, AND ELECTRONIC COMPONENT

ABSTRACT

Provided is a laminate that suffers little wiring corrosion during storage under high temperature and high humidity conditions. It is a laminate including a metal wire (M1) with a thickness of 0.1 to 5 μm , a relief pattern of an organic insulating film (P1) with a thickness of 0.5 to 4 μm , and a metal wire (M2) with a thickness of 0.1 to 5 μm which are disposed in this order on a piezoelectric substrate, wherein the organic insulating film (P1) includes a cured product obtainable by curing a photosensitive resin composition containing an alkali soluble resin (A) and a naphthoquinone diazide compound (E), the naphthoquinone diazide compound (E) accounting for 5 to 25 parts by mass relative to 100 parts by mass of the alkali soluble resin (A), and the ion elution quantity from the organic insulating film (P1) being 2,000 ppm or less as determined by an ion elution quantity measurement method.

Figure 3